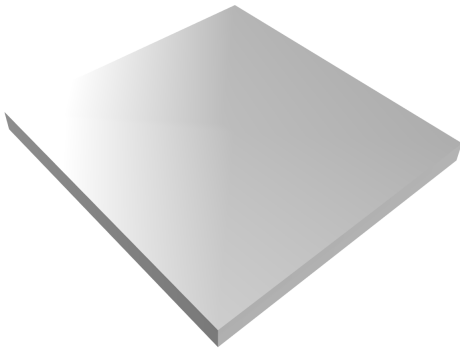
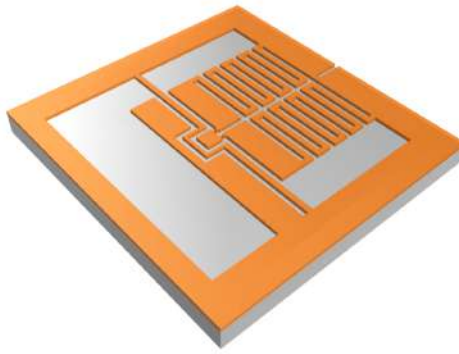


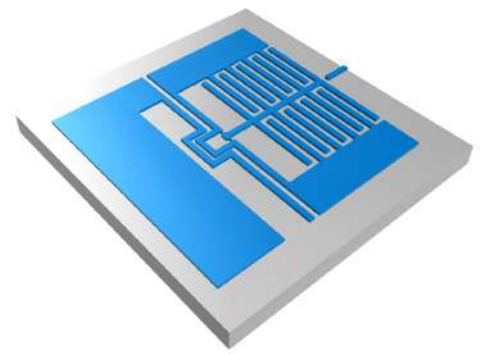
1.  
Substrate cleaning



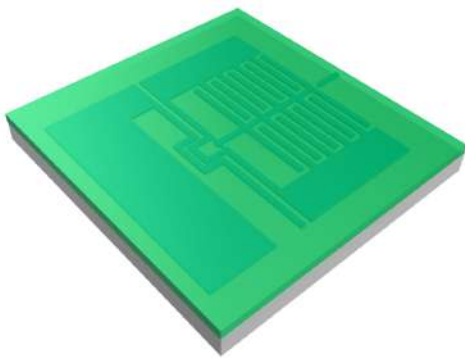
2.  
Resist patterning (EBL)



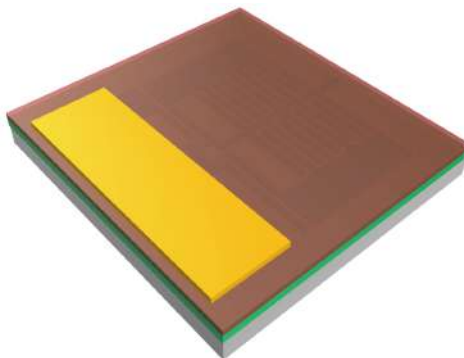
3.  
Al sputtering and lift-off



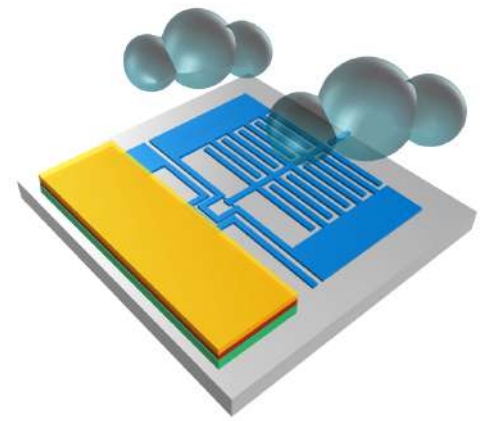
4.  
aSi deposition (PECVD)



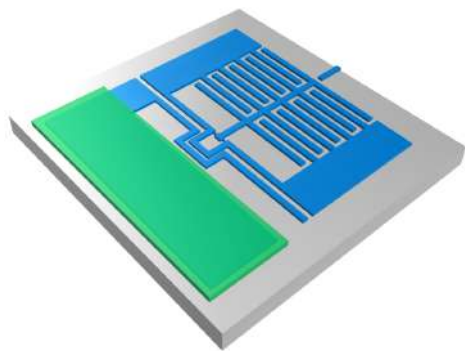
5.  
Resist patterning (EBL)



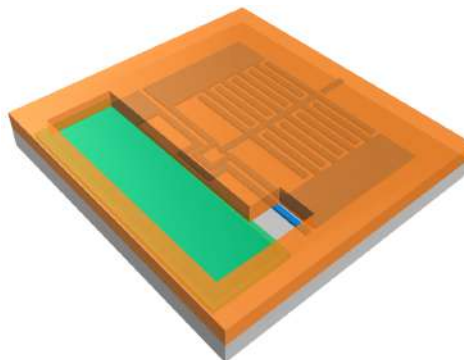
6.  
RIE etching (SF6 & He)



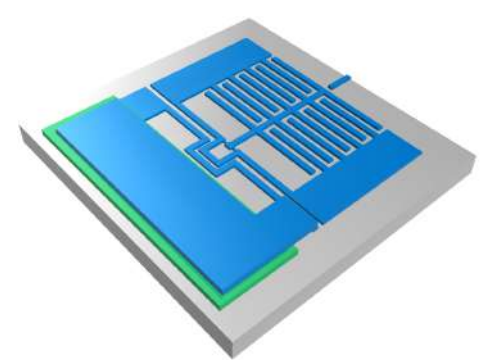
7.  
O2 Plasma ashing



8.  
Resist patterning (EBL)



9.  
Al sputtering and lift-off



■ Si   ■ CSAR 64.09   ■ Al   ■ PMMA 950K A4   ■ ARN 7700/18   ■ aSi